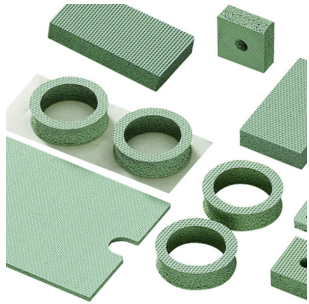


# Data sheet Product WSF 08



Accessories for electronic components>Thermal interface material>Heat conductive foam and gel foils

- elastomer foam with closed cell structure
- good heat conductor e.g. between components, heatsinks and casing parts
- electrical insulating
- can be compressed even with a low contact pressure
- absorbs shocks and vibrations

### Thermal resistance at 3.2 mm material thickness:

compression [%]	contact	10	25	50
contact pressure [psi]	>1	5	12	34
$R_{th}$ [K/W] (1 in <sup>2</sup> x 3.2 mm)	6	4.5	2.5	1
heat conductivity [W/mK]	0.3	0.4	0.45	0.65

- **WSFS 635** double sided adhesive and **WSF** self-adhesive upon request
- according to NASA gas emission requirements

## Features

material:

foam film

Material:

10mm 11111

material thickness:	<b>0.8<sup>±0,400</sup> mm</b>
version:	<b>non adhesive</b>
colour:	<b>green</b>
density:	<b>1.105 g/cm<sup>3</sup></b>
hardness:	<b>13 Shore A</b>
temperature range:	<b>-62°C ... +205°C</b>
thermal conductivity:	<b>0.108 W/m·K (substrate)</b>
compression, 25%:	<b>18 psi</b>
elongation:	<b>150 %</b>
tear strength:	<b>120 psi</b>
dielectric strength:	<b>4 kV/mm</b>
class of inflammability:	<b>UL 94 V-1 (at thickness ≥3.2mm)</b>
type of delivery:	<ul style="list-style-type: none"> <li>• <b>plates, usable area 914x914mm</b></li> <li>• <b>other dimensions upon request</b></li> </ul>